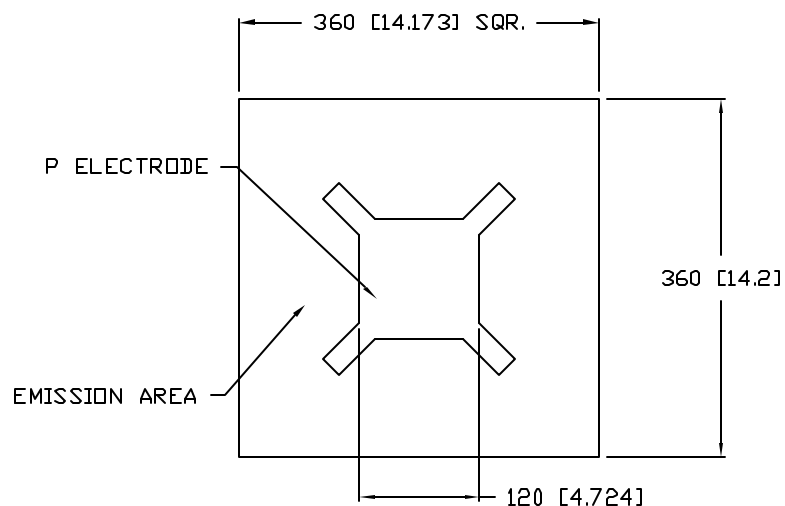


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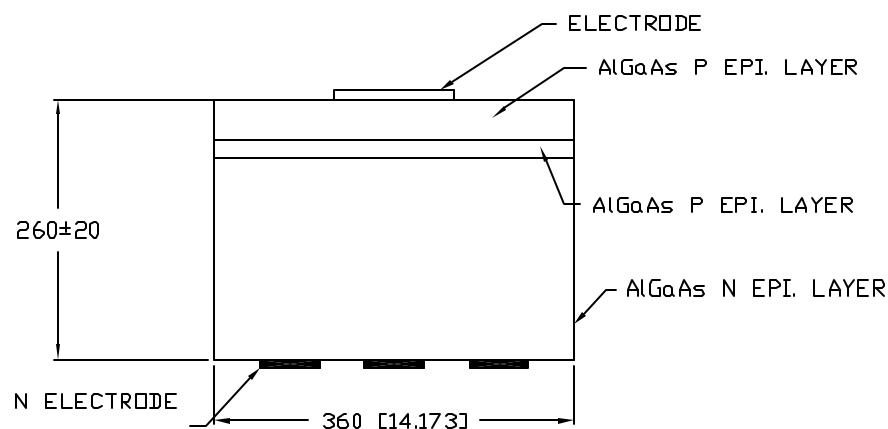
SSD-LX014E950DGPU

REV.



ELECTRO-OPTICAL CHARACTERISTICS:

PARAMETER	SYMBOL	TEST COND	MIN	TYP	MAX	UNITS
FORWARD VOLTAGE	V_f	$I_f=20\text{mA}$		1.18	1.4	V
REVERSE CURRENT	I_r	$V_r=5\text{V}$			10	μA
PEAK WAVELENGTH	λ_p	$I_f=20\text{mA}$	935	950	960	nm
SPECTRA HALF-WIDTH		$I_f=20\text{mA}$		50		nm
RADIANT POWER	P_o	$I_f=20\text{mA}$	1.2	2.0		mW



CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

NOTES:

1. UNITS: μm
2. WIRE BOND METALLIZATION: GOLD.
3. P SIDE UP ON WAFER.



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950nm IR CHIP.

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RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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APPROVED BY:

DATE: 10.1.03

PAGE: 1 OF 1

SCALE: N/A